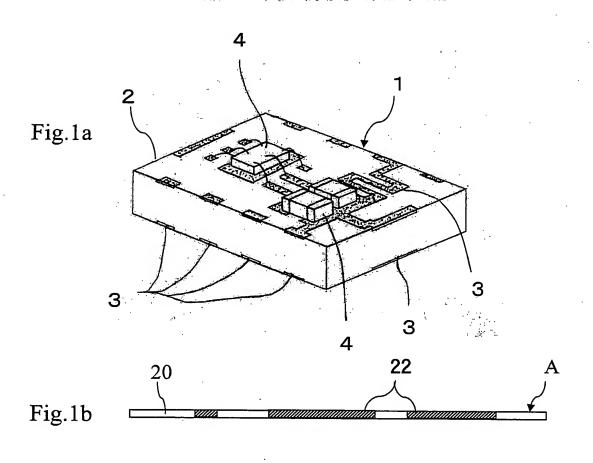
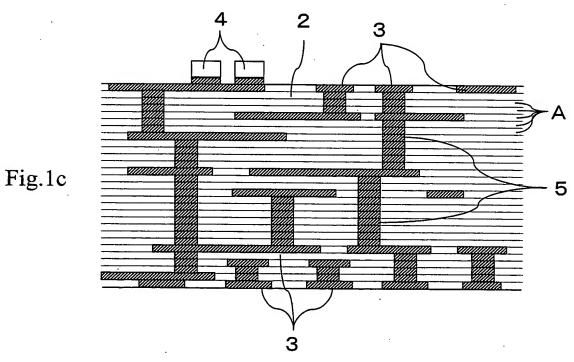
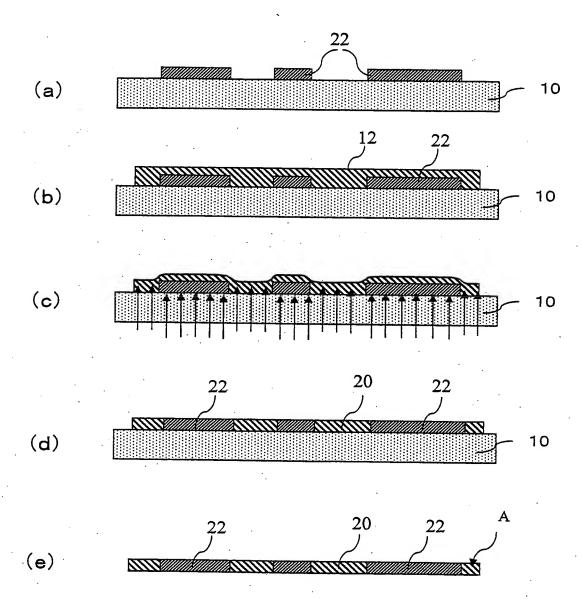
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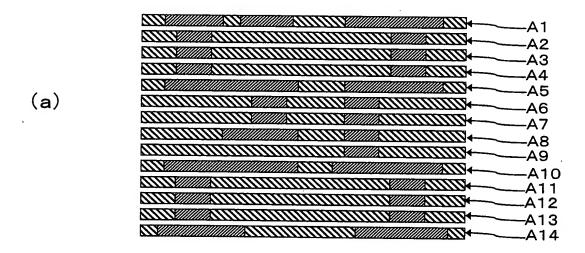
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Fig.2



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Fig.3



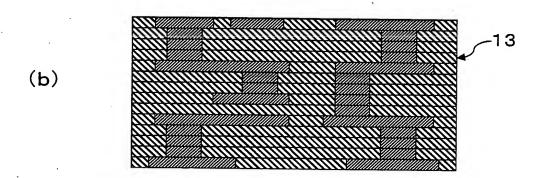
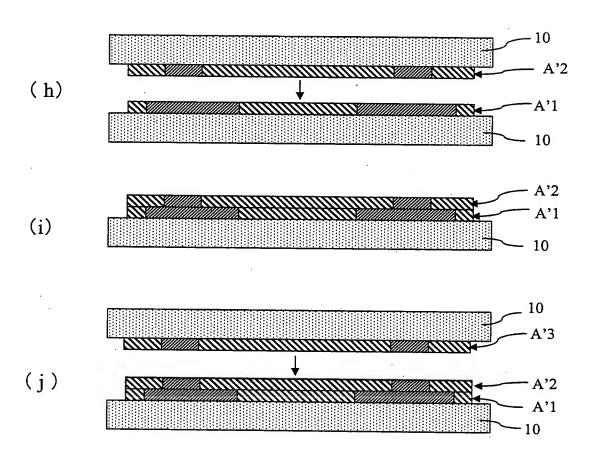
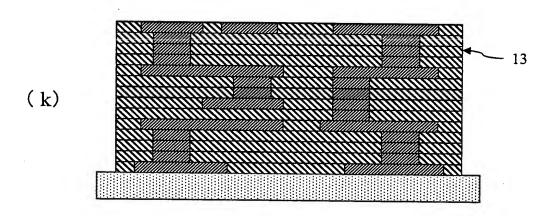


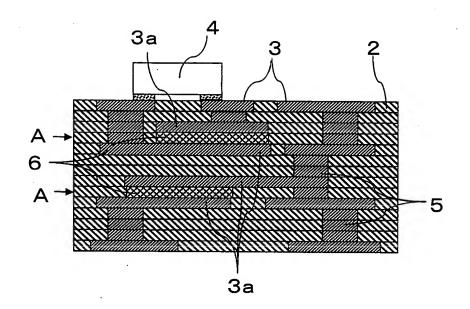
Fig.4





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Fig. 5



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Fig. 6

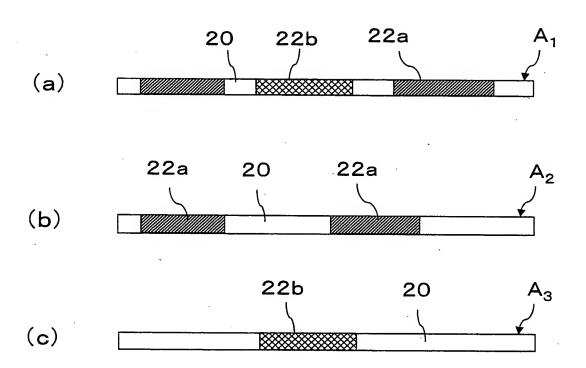


Fig. 7

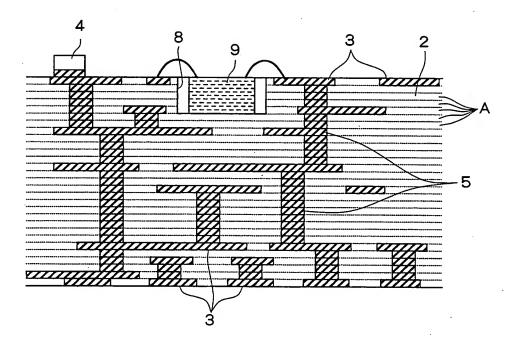
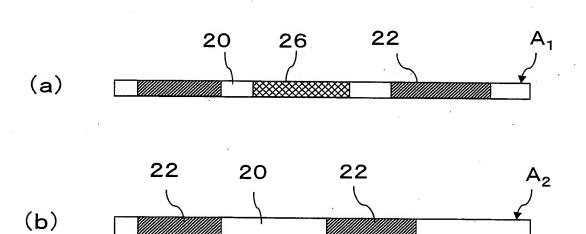


Fig. 8



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Fig. 9

